CLAIMS

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- 1. Adhesive composition for use in the manufacture of wood-based boards, said adhesive composition containing resin, a filler, a foaming agent and a solvent, and said composition being foamable, characterized in that the adhesive composition contains 40 80 w-% resin, 5 30 w-% filler, 0 40 w-% solvent, and 0.1 10 w-% foaming agent selected from organic and/or inorganic surface-active sulfate, sulfonate, phosphate or phosphonate compounds or their derivatives or mixtures.
- 2. Adhesive composition according to claim 1, characterized in that the foaming agent is lauryl sulfate, lauryl ether sulfate, benzene sulfate or a compound, derivative or mixture of these.
- 3. Adhesive composition according to claim 2, characterized in that the lauryl sulfate or lauryl ether sulfate has been selected from the group: sodium lauryl sulfate, ammonium lauryl sulfate, potassium lauryl sulfate, sodium lauryl ether sulfate, ammonium lauryl ether sulfate, potassium lauryl ether sulfate, a derivative of these or a mixture of these or the like.
- 4. Adhesive composition according to claim 1
 25 or 2, characterized in that the foaming agent
 has been selected from the group: sodium isopropyl
 sulfonate, sodium lauryl sulfonate, sodium benzene
 sulfonate, sodium alkyl benzene sulfonate, ammonium
 lauryl phosphate, ammonium lauryl sulfonate, potassium
 30 olein sulfate, sodium naphthalene sulfonate or a compound, derivative or mixture of these or the like.
 - 5. Adhesive composition according to any one of claims 1 4, characterized in that the composition contains 0.1 5 w-% foaming agent.
- of claims 1 5, characterized in that the adhesive composition contains 1 10 w-% foaming agent,

of which 0.1 - 30 w-% consists of lauryl sulfate, lauryl ether sulfate, benzene sulfate or compounds, derivatives or mixtures of these.

- 7. Adhesive composition according to any one of claims 1 - 6, characterized in that the 5 resin has been selected from the group: UF, MUF, MUFP, PF, PMF, PRF, a derivative of these or a mixture of these or the like.
- 8. Adhesive composition according to any one of claims 1 - 7, characterized in that the 10 composition contains 50 - 70 w-% resin.
 - 9. Adhesive composition according to any one of claims 1 - 8, characterized in that the composition contains 8 - 20 w-% filler.
- 10. Adhesive composition according to any one 15 of claims 1 - 9, characterized in that the filler has been selected from the group: starch, wheat meal, chalk, sodium carbonate, potassium carbonate, calcium carbonate, ammonium sulfate, wood powder, quebracho or a derivative or mixture of these or the 20 like.
 - 11. Adhesive composition according to any one of claims 1 - 10, characterized in that the composition contains 12 - 35 w-% solvent.
- 12. Adhesive composition according to any one 25 of claims 1 - 11, characterized in that the solvent is water or an organic solvent.

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- 13. Adhesive composition according to any one of claims 1 - 12, characterized in that the adhesive composition contains air added to it.
- 14. Adhesive composition according to any one of claims 1 - 13, characterized in that the foaming agent is in solid, liquid or paste-like state.
- 15. Adhesive composition according to any one of claims 1 - 14, characterized in that the 35 adhesive composition has been produced by mixing the

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resin, filler, foaming agent and solvent together to form an emulsion.

of claims 1 - 15, characterized in that the adhesive composition has been produced by mixing the resin, filler, foaming agent and solvent together at a temperature of over 40 °C.